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TFT Display Module

Part Number

E50RG14885LBAM500-C

Overview

480x854(67.56x122.35), 3.3V, 3SPI+16/18/24bit RGB, White LED backlight, IPS, Wide temp, Transmissive-Normally Black, Capacitive Touch Screen, LCD Driver:ILI9806E, CTP Driver: GT911 500 NITS, RoHS Compliant

* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silicon TFT as a switching device. This model is composed of a Transmissive type TFT-LCD Panel, driver circuit, back-light unit. The resolution of a 5.0'TFT-LCD contains 480x854 pixels, and can display up to 65K/262K/16.7M colors.

* Features

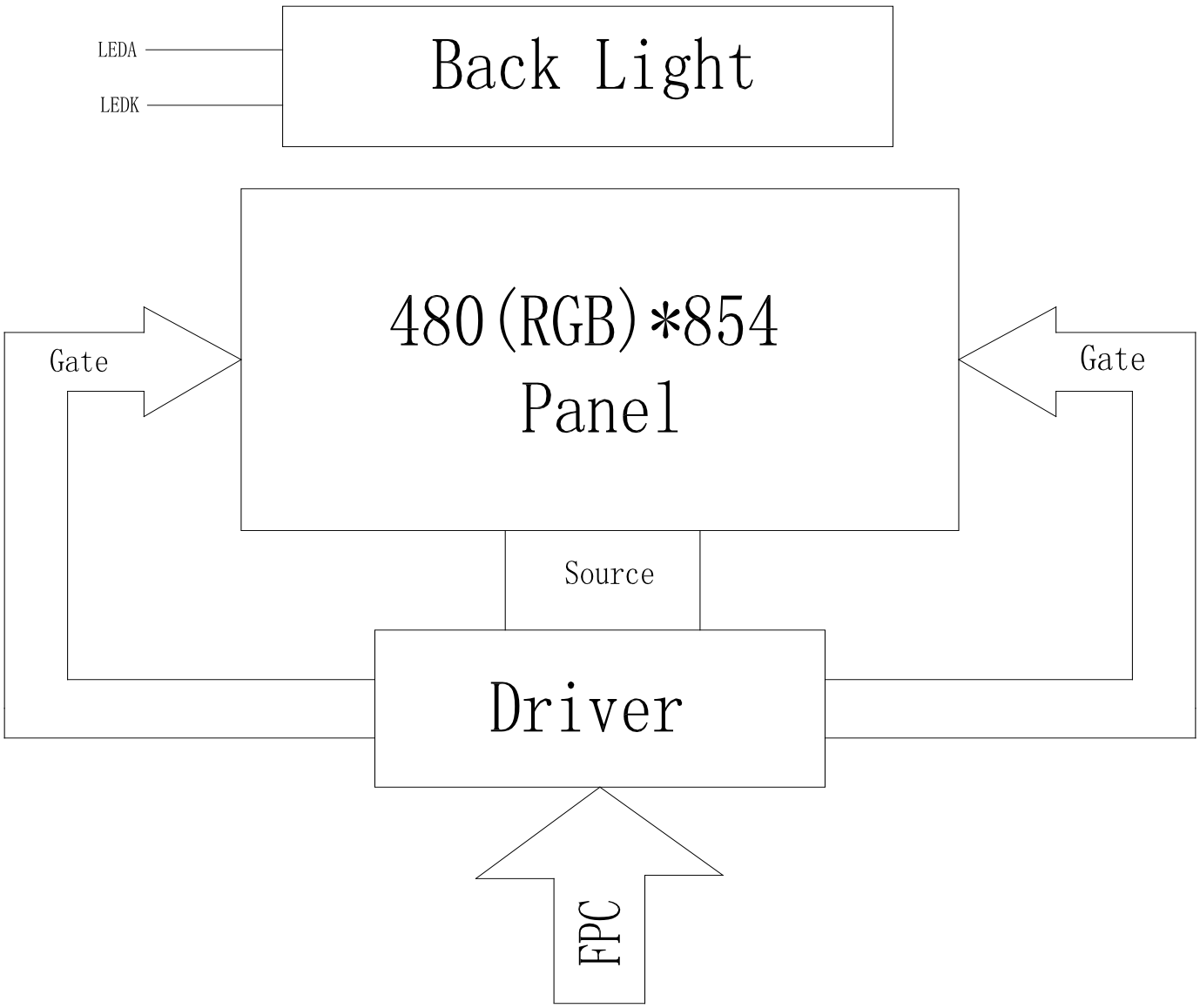
-Low Input Voltage: 3.3V(TYP)
-Display Colors of TFT LCD: 65K/262K/16.7M colors
-Interface: 3-SPI+16/18/24-bits RGB interface.
-CTP Interface: I2C

General Information Items	Specification	Unit	Note
	Main Panel		
Display area(AA)	61.632(H)*109.6536(V) (5.0inch)	mm	-
CTP View area	62.16(H)*110.53(V)	mm	
Driver element	TFT active matrix	-	-
Display colors	65K/262K/16.7M	colors	-
Number of pixels	480(RGB)*854	dots	-
TFT Pixel arrangement	RGB vertical stripe	-	-
Pixel pitch	0.1284(H)*0.1284(V)	mm	-
Viewing angle	ALL	o'clock	-
TFT Controller IC	ST7701	-	-
CTP Driver IC	GT911		
Display mode	Transmissive/Normally Black	-	-
Touch mode	5-point and Gestures		
Operating temperature	-20～+70	℃	-
Storage temperature	-30～+80	℃	-

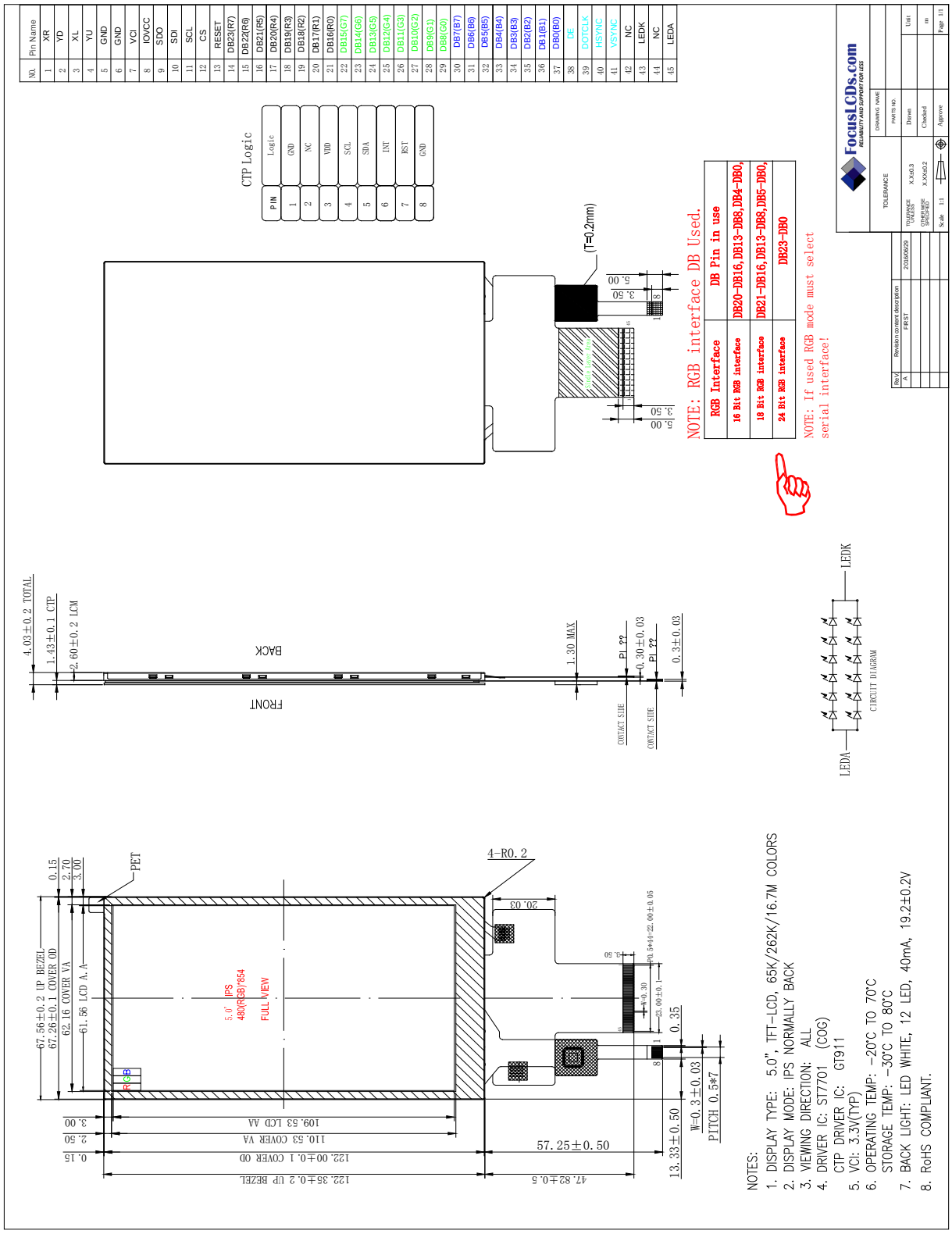
* Mechanical Information

Item		Min.	Typ.	Max.	Unit	Note
Module size	Horizontal(H)		67.56		mm	-
	Vertical(V)		122.35		mm	-
	Depth(D)		4.03		mm	-
Weight			--		g	-

1. Block Diagram



2. Outline dimension



3. Input terminal Pin Assignment

3.1 TFT

NO.	SYMBOL	DISCRIPTION	I/O
1	XR(NC)	Touch panel Right Glass Terminal	A/D
2	YD(NC)	Touch panel Bottom Film Terminal	A/D
3	XL(NC)	Touch panel LIFT Glass Terminal	A/D
4	YU(NC)	Touch panel Top Film Terminal	A/D
5	GND	Ground.	P
6	GND	Ground.	P
7	VCI	Supply voltage (3.3V).	P
8	VDDIO	I/O power supply voltage.	P
9	SDO	SPI interface output pin.-The data is output on the falling edge of the SCL signal.-If not used, let this pin open.	O
10	SDI	Data lane in 1 data lane serial interface. The data is latched on the rising edge of the SCL signal.	I
11	SCL	This pin is used to select “Data or Command” in the parallel interface. When D/CX = ’1’, data is selecte d. When D/CX = ’0’, command is selected. This pin is used serial interface clock in 3-wire 9-bit / 4- wire 8-bit serial data interface. fix this pin at VCI or GND when not in use.	I
12	CS	Chip select input pin (“Low” enable). fix this pin at VCI or GND when not in use.	I
13	RESET	Reset pin. Setting either pin low initializes the LSI. Must be reset after power is supplied.	I
14-37	DB23-DB0	24-bit parallel bi-directional data bus for MCU system and RGB interface mode .Fix to GND level when not in use	I/O
38	DE	Data enable signal for RGB interface peration. fix this pin at VCI or GND when not in use.	I
39	DOTCLK	Dot clock signal for RGB interface operation. Fix this pin at VCI or GND when not in use.	I
40	HSYNC	Line synchronizing signal for RGB interface o peration.	I

		fix this pin at VCI or GND when not in use.	
41	VSYNC	Frame synchronizing signal for RGB interface operation. fix this pin at VCI or GND when not in use.	I
42	NC		
43	LEDK	Cathode pin of backlight.	P
44	NC		
45	LEDA	Anode pin of backlight.	P

3.2 CTP

NO.	SYMBOL	DISCRIPTION	I/O
1	GND	Ground.	P
2	NC		
3	VDD	Supply voltage.	P
4	SCL	I2C clock input.	I
5	SDA	I2C data input and output	I/O
6	INT	External interrupt to the host.	I
7	RST	External Reset, Low is active.	I
8	GND	Ground.	P

4. LCD Optical Characteristics

4.1 Optical specification

Item		Symbol	Condition	Min.	Typ.	Max.	Unit.	Note
Contrast Ratio		CR	Θ=0 Normal viewing angle	640	800	--		(1)(2)
Response time	Rising	T_R		--	16	21	msec	(1)(3)
	Falling	T_F		--	19	24		
Color gamut		S(%)		--	70	--	%	C-light
Color Filter Chromacicity	White	W_X		--	0.305	--	-	(1)(4) CF glass
		W_Y		--	0.340	--		
	Red	R_X		--	--	--		
		R_Y		--	--	--		
	Green	G_X		--	--	--		
		G_Y		--	--	--		
	Blue	B_X		--	--	--		
		B_Y		--	--	--		
Viewing angle	Hor.	Θ_L	CR>10	--	80	--	-	(1)(4) Measuring with Polarizer, Reference Only
		Θ_R		--	80	--		
	Ver.	Θ_U		--	80	--		
		Θ_D		--	80	--		
Option View Direction		Free						

4.2 Measuring Condition

■ Measuring surrounding：dark room

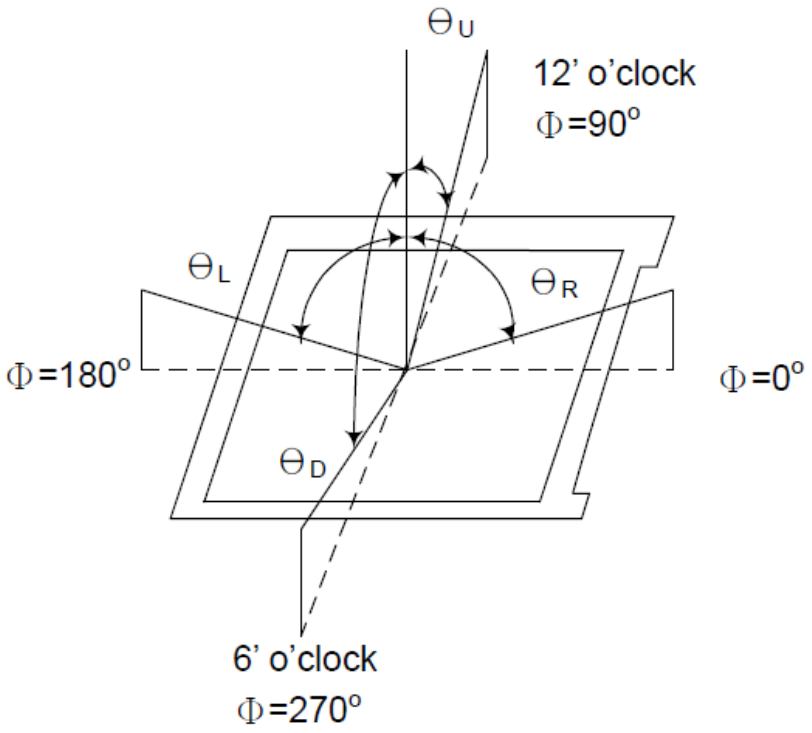
■ Ambient temperature：25±2℃

■ 15min. warm-up time.

4.3 Measuring Equipment

- FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

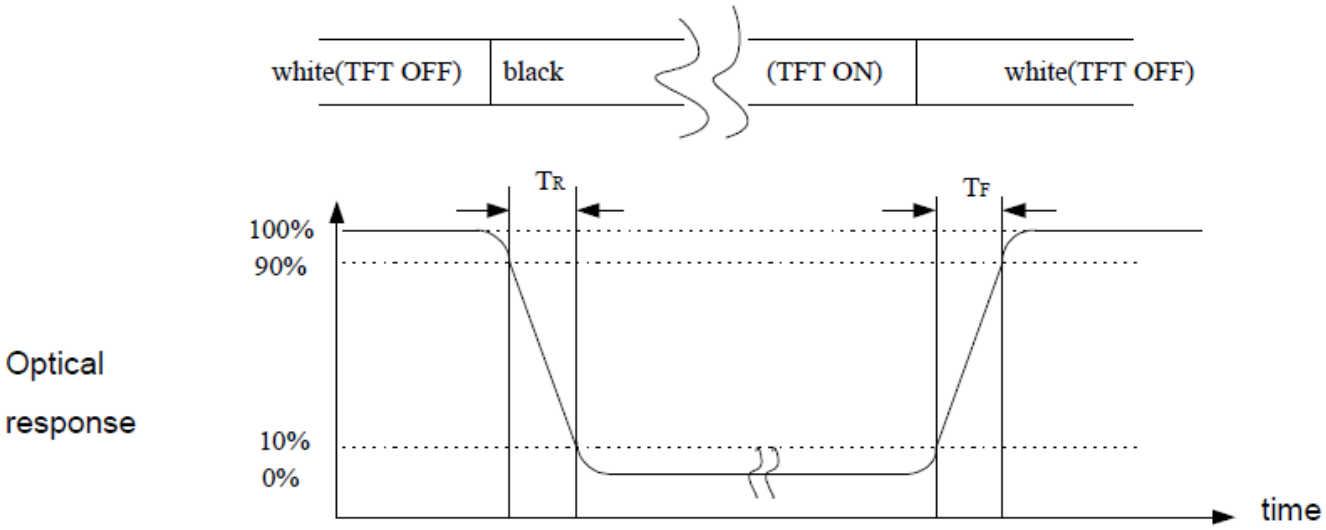
Note (1) Definition of Viewing Angle:



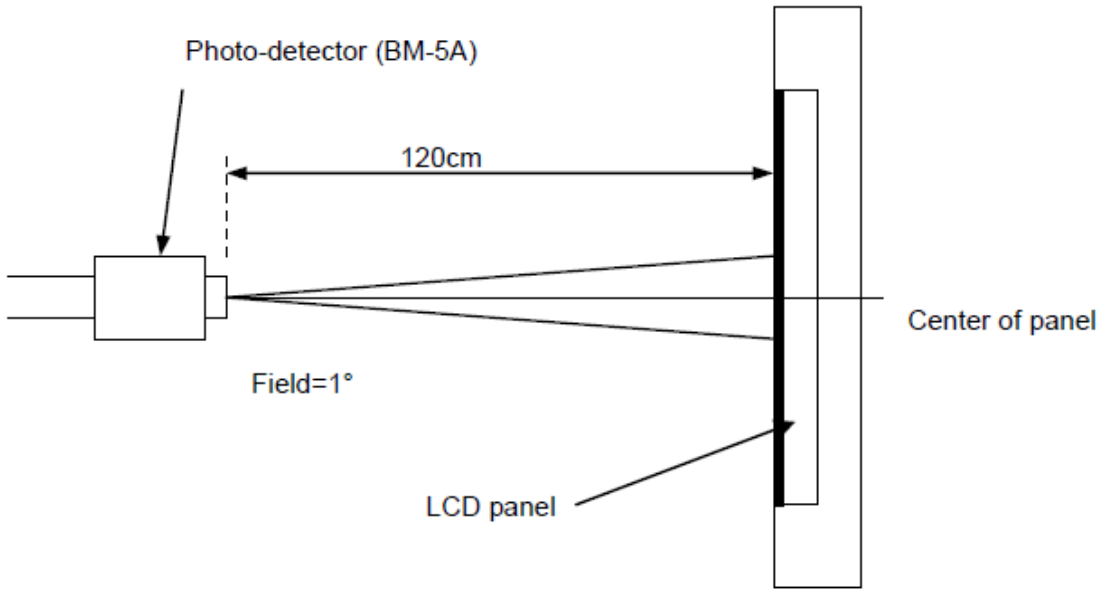
Note (2) Definition of Contrast Ratio (CR) :
measured at the center point of panel

$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

Note (3) Definition of Response Time : Sum of T_R and T_F



Note (4) Definition of optical measurement setup



5. TFT Electrical Characteristics

5.1 Absolute Maximum Rating (Ta=25 VSS=0V)

Characteristics	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VDD	-0.3	4.8	**V**
Digital interface supple Voltage	VDDIO	-0.3	4.6	**V**
Operating temperature	T_{OP}	-20	+70	℃
Storage temperature	T_{ST}	-30	+80	℃

NOTE: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

5.2 DC Electrical Characteristics

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Note
Digital Supply Voltage	VDD	2.5	2.8/3.3	4.8	V	--
Digital interface supple Voltage	VDDIO	1.65	1.8	3.3	V	--
Normal mode Current consumption	IDD	--	30	--	mA	--
Level input voltage	V_{IH}	$0.7V_{DDIO}$	--	V_{DDIO}	V	--
	V_{IL}	-0.3	--	$0.3V_{DDIO}$	V	--
Level output voltage	V_{OH}	$0.8*V_{DDIO}$	--	V_{DDIO}	V	--
	V_{OL}	GND	--	$0.2V_{DDIO}$	V	--

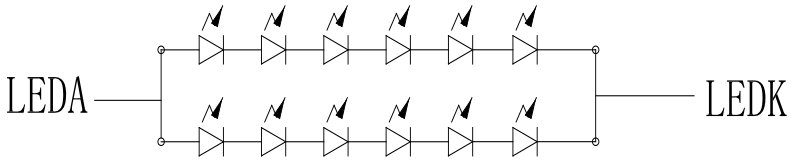
5.3 LED Backlight Characteristics

The back-light system is edge-lighting type with 12 chips White LED

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Forward Current	I_F	30	40	--	mA	--
Forward Voltage	V_F	--	19.2	--	V	--
LCM Luminance	L_V	--	520	--	cd/m2	Note3
LED life time	Hr	50000			Hour	Note1,2
Uniformity	AVg	80	--	--	%	Note3

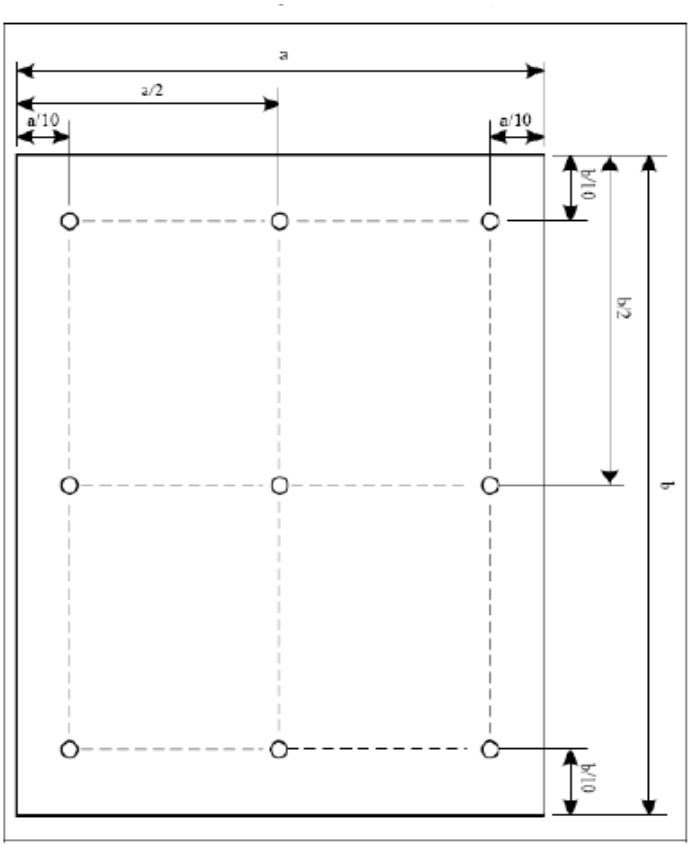
Note (1) LED life time (Hr) can be defined as the time in which it continues to operate under the condition: Ta=25±3 ℃, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note (2) The “LED life time” is defined as the module brightness decrease to 50% original brightness at Ta=25℃ and IL=40mA. The LED lifetime could be decreased if operating IL is larger than 40mA. The constant current driving method is suggested.



CIRCUIT DIAGRAM

NOTE 3：Luminance Uniformity of these 9 points is defined as below:



$$\text{Uniformity} = \frac{\text{minimum luminance in 9 points (1-9)}}{\text{maximum luminance in 9 points (1-9)}}$$

$$\text{Luminance} = \frac{\text{Total Luminance of 9 points}}{9}$$

6. TFT AC Characteristic

6.1 Display Serial Interface Timing Characteristics (3-line SPI system)

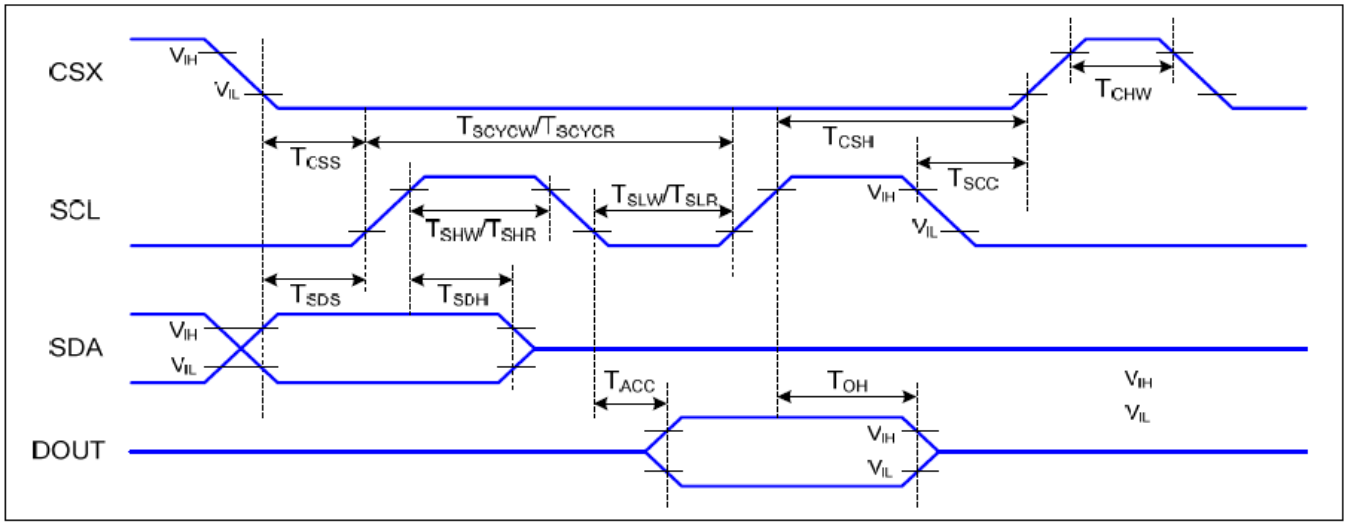


Figure 1 3-line serial Interface Timing Characteristics

VDDI=1.8,VDD=2.8, AGND=DGND=0V, Ta=25℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	60		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	66		ns	
	T_{SHW}	SCL "H" pulse width (Write)	15		ns	
	T_{SLW}	SCL "L" pulse width (Write)	15		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA (DIN)	T_{SDS}	Data setup time	10		ns	
	T_{SDH}	Data hold time	10		ns	

Table 4 3-line serial Interface Characteristics

Note : The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

6.2 Parallel RGB Interface Timing Characteristics

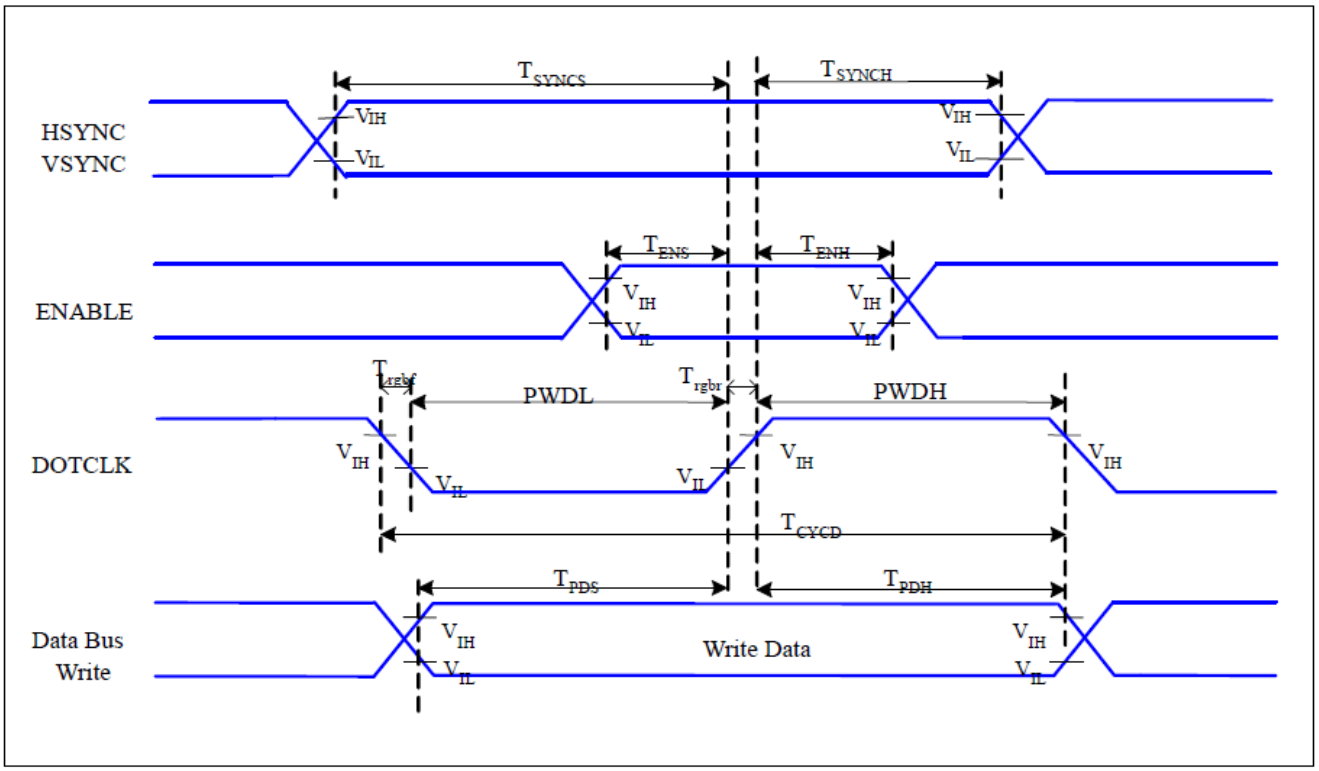


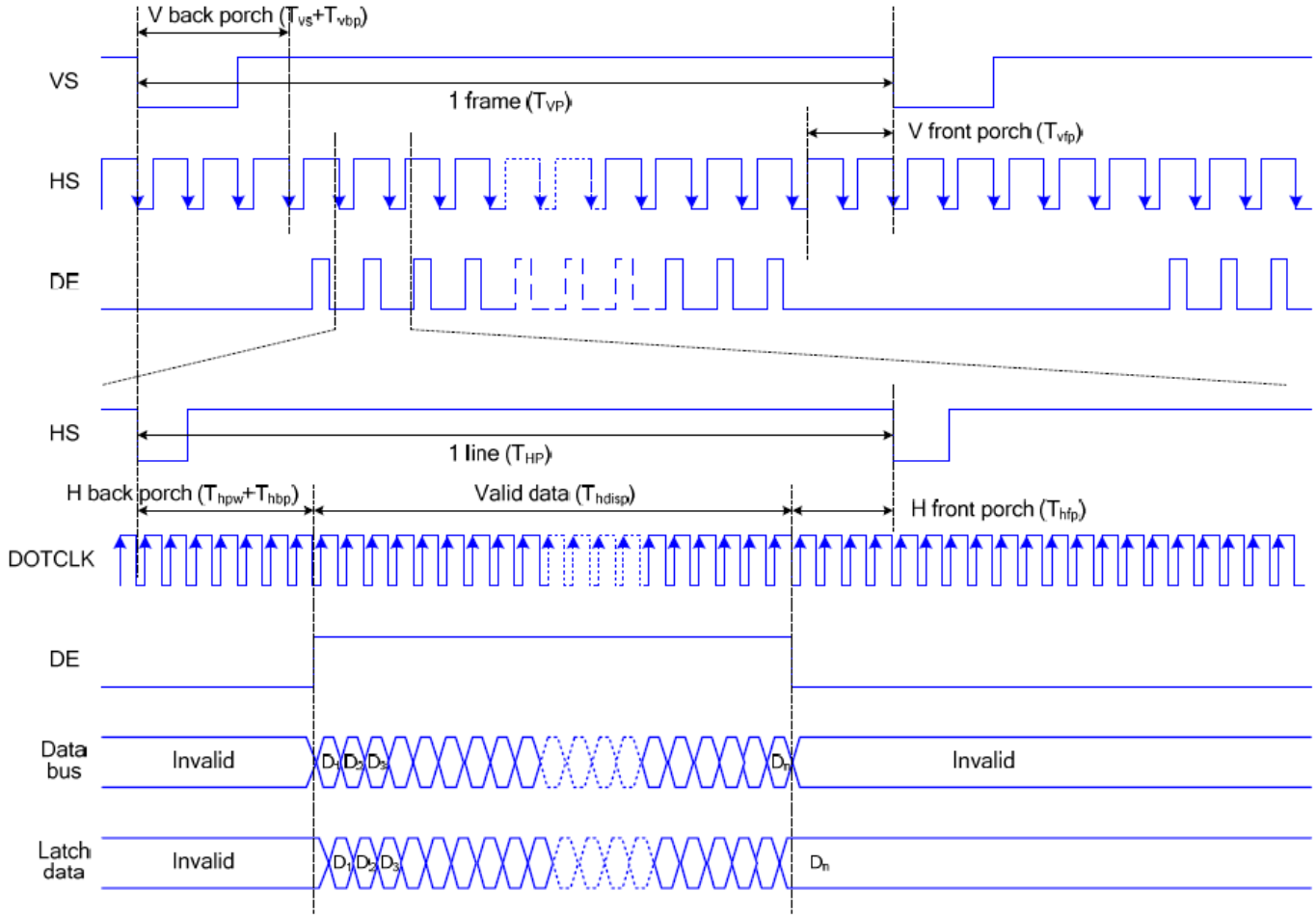
Figure 4 RGB Interface Timing Characteristics

VDDI=1.8,VDD=2.8, AGND=DGND=0V, Ta=25 ℃

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T_{SYNCS}	VSYNC, HSYNC Setup Time	5	-	ns	
ENABLE	T_{ENS}	Enable Setup Time	5	-	ns	
	T_{ENH}	Enable Hold Time	5	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	13	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	13	-	ns	
	T_{CYCD}	DOTCLK Cycle Time	28	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	15	ns	
DB	T_{PDS}	PD Data Setup Time	5	-	ns	
	T_{PDH}	PD Data Hold Time	5	-	ns	

Table 7 18/16 Bits RGB Interface Timing Characteristics

The timing chart of RGB interface DE mode is shown as follows.



Note: The setting of front porch and back porch in host must match that in IC as this mode.

Figure 28 Timing Chart of Signals in RGB Interface DE Mode

The timing chart of RGB interface HV mode is shown as follows.

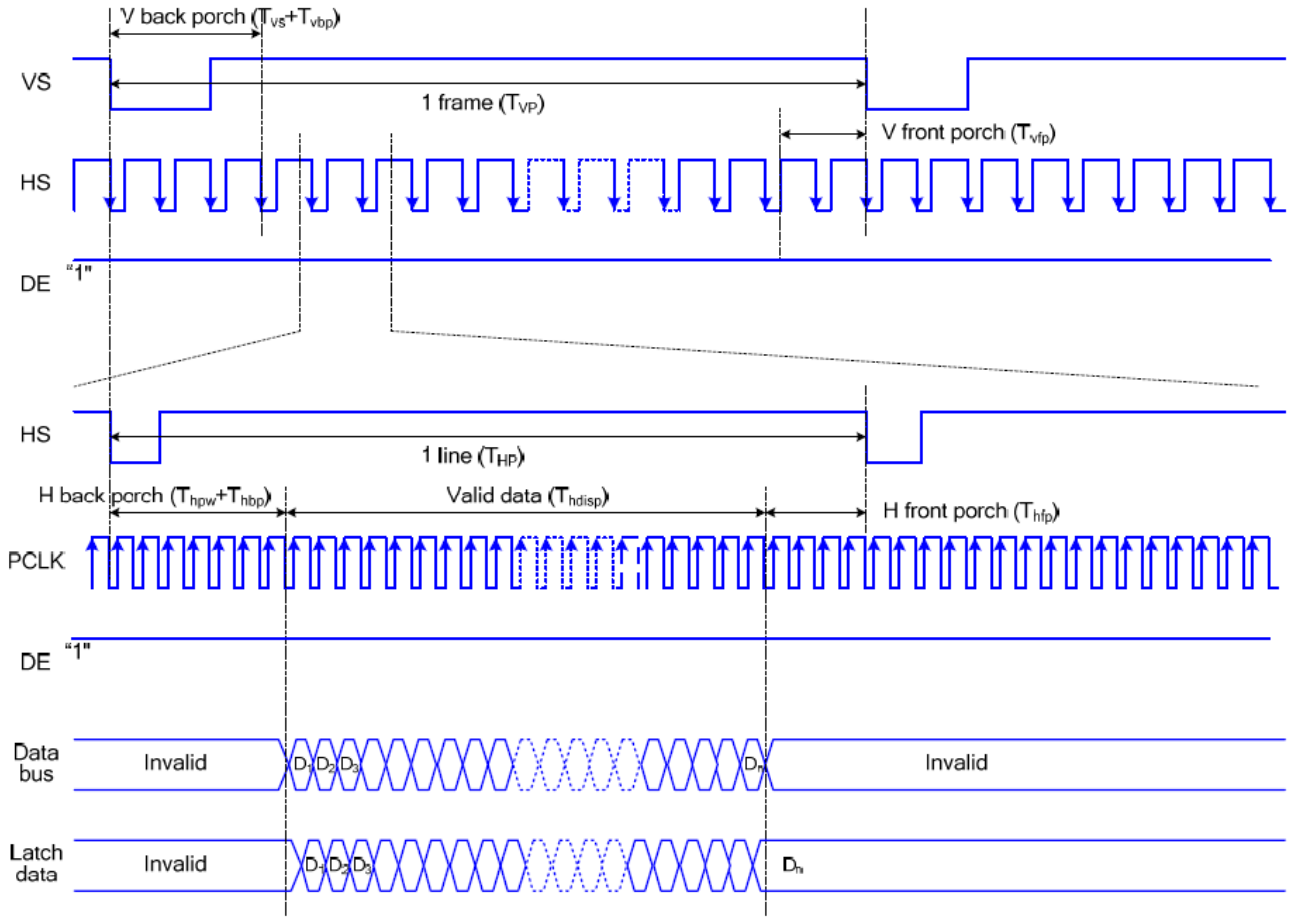


Figure 29 Timing chart of RGB interface HV mod

6.3 DPI Interface Timing

The display operation via the RGB interface is synchronized with the VSYNC, HSYNC, and DOTCLK signals.

The data can be written only within the specified area with low power consumption by using window addressfunction.

The back porch and front porch are used to set the RGB interface timing.

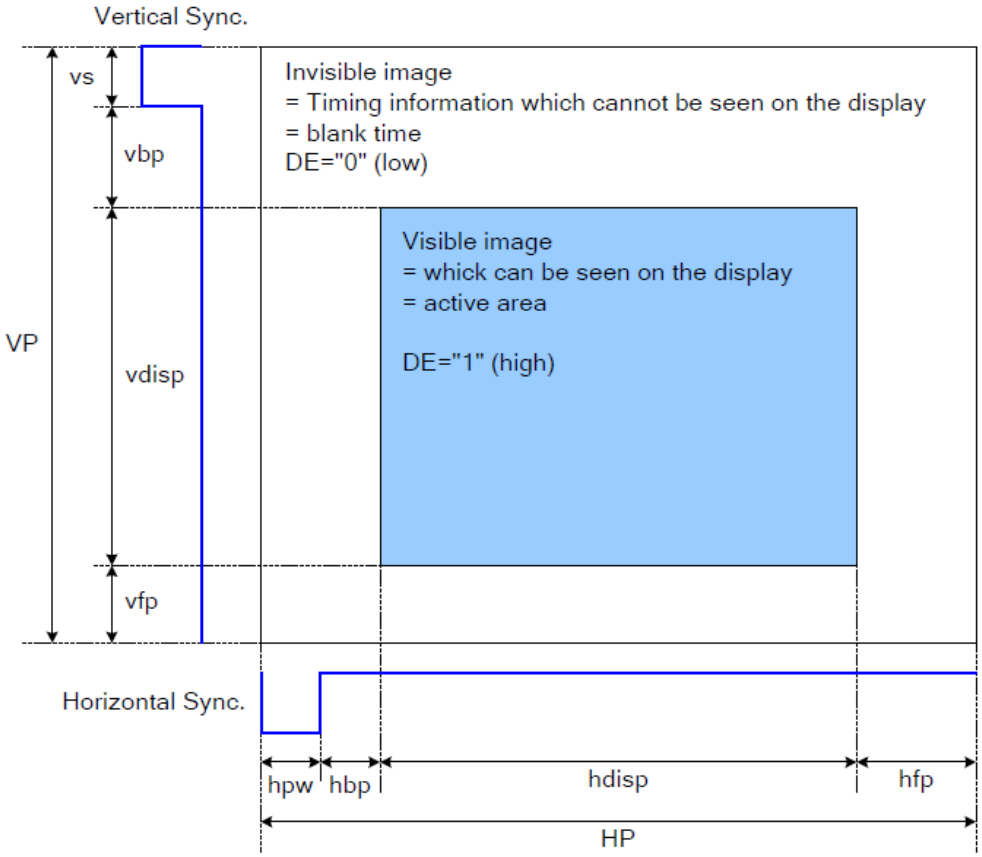


Figure 27 DRAM Access Area by RGB Interface

Please refer to the following table for the setting limitation of RGB interface signals.

Parameter	Symbol	Min.	Typ.	Max.	Unit
Horizontal Sync. Width	hpw	TBD	TBD	TBD	Clock
Horizontal Sync. Back Porch	hbp	TBD	TBD		Clock
Horizontal Sync. Front Porch	hfp	TBD	TBD	-	Clock
Vertical Sync. Width	vs	TBD	TBD	TBD	Line
Vertical Sync. Back Porch	vbp	TBD	TBD		Line
Vertical Sync. Front Porch	vfp	TBD	TBD	-	Line

Note:

1. *Typical value are related to the setting of dot clock is TBDMHz and frame rate is TBDHz..*
2. *If the setting of hpw is TBDdot clocks and hbp is TBD dot clocks, the setting of HBP in command B1h is TBD dot clocks*
3. *In with ram mode, hpw+hbp+hfp≧TBD*
4. *In without ram mode, hpw+hbp≧TBD*

6.4 Reset input timing

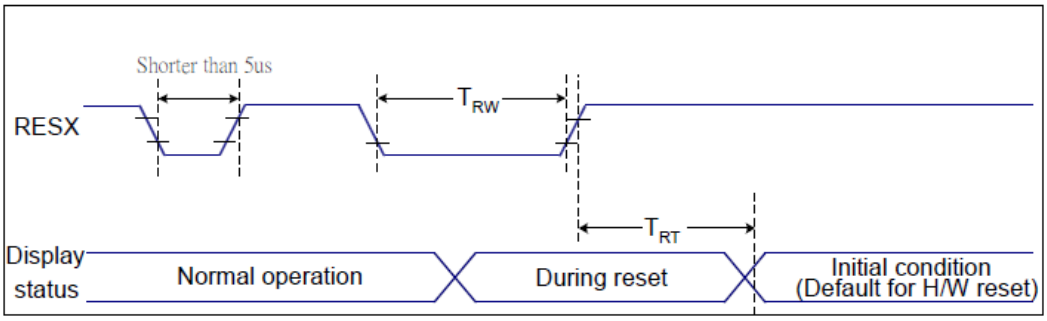


Figure 10 Reset Timing

VDDI=1.8,VDD=2.8, AGND=DGND=0V, Ta=25 ℃

Related Pins	Symbol	Parameter	MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1, 5)	ms
				120(Note 1, 6, 7)	ms

Table 10 Reset Timing

Notes:

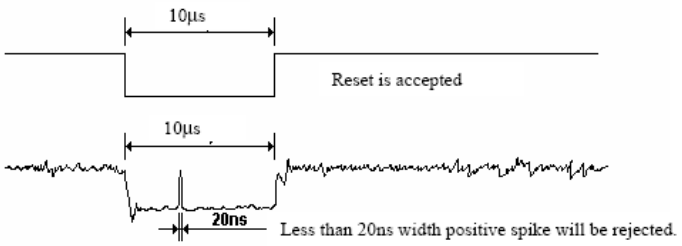
1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.

4. Spike Rejection also applies during a valid reset pulse as shown below:



5. When Reset applied during Sleep In Mode.

6. When Reset applied during Sleep Out Mode.

7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

7. CTP Specification

7.1 Electrical Characteristics

7.1.1 Absolute Maximum Rating

Item	Symbol	Min.	Max.	Unit	Note
Power Supply Voltage	VDD	2.66	3.47	V	--
Operating temperature	T_{OP}	-40	+85	℃	--
Storage temperature	T_{ST}	-60	+125	℃	--
Welding temperature (10s)	--	--	300	℃	--
ESD protection voltage (HB Model)	--	--	±2	KV	--

7.1.2 DC Electrical Characteristics (Ta=25℃)

(Ambient temperature:25℃, AVDD=2.8V, VDDIO=1.8V or VDDIO=AVDD)

Item	Min.	Typ.	Max.	Unit	Note
Normal mode operating current	--	8	14.5	mA	
Green mode operating current	--	3.3	--	mA	
Sleep mode operating current	70	--	120	uA	
Doze mode operating current	--	0.78	--	mA	
Digital Input low voltage/VIL	-0.3	--	0.25*VDDIO	V	
Digital Input high voltage/VIH	0.75*VDDIO	--	VDDIO+0.3	V	
Digital Output low voltage/VOL	--		0.15*VDDIO	V	
Digital Output high voltage/VOH	0.85*VDDIO			V	

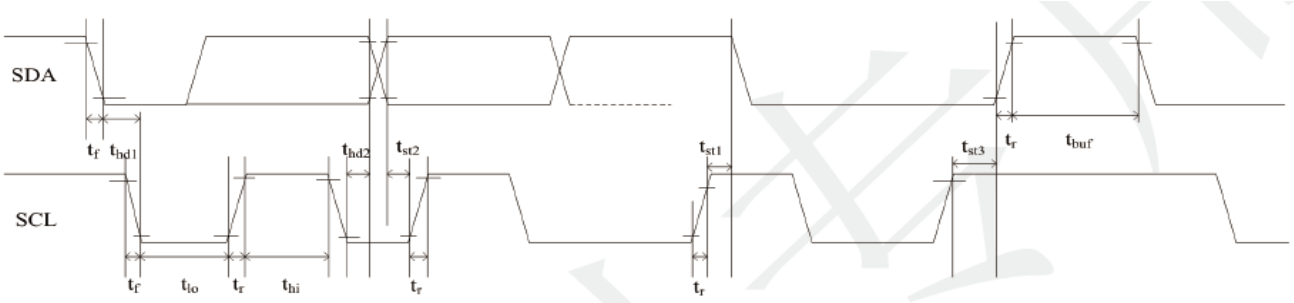
7.1.3 AC Characteristics

(Ambient temperature:25℃, AVDD=2.8V, VDDIO=1.8V)

Parameter	Min	Typ	Max	Unit
OSC oscillation frequency	59	60	61	MHZ
I/O output rise time,low to high	-	14	-	ns
I/O output rfall time,high to low	-	14	-	ns

7.2 I2C Timing

GT911 provides a standard I2C interface for SCL and SDA to communicate with the host. GT911 always serves as slave device in the system with all communication being initialized by the host. It is strongly recommended that transmission rate be kept at or below 400Kbps. The I2C timing is shown below:



Test condition 1: 1.8V host interface voltage, 400Kbps transmission rate, 2K pull-up resistor

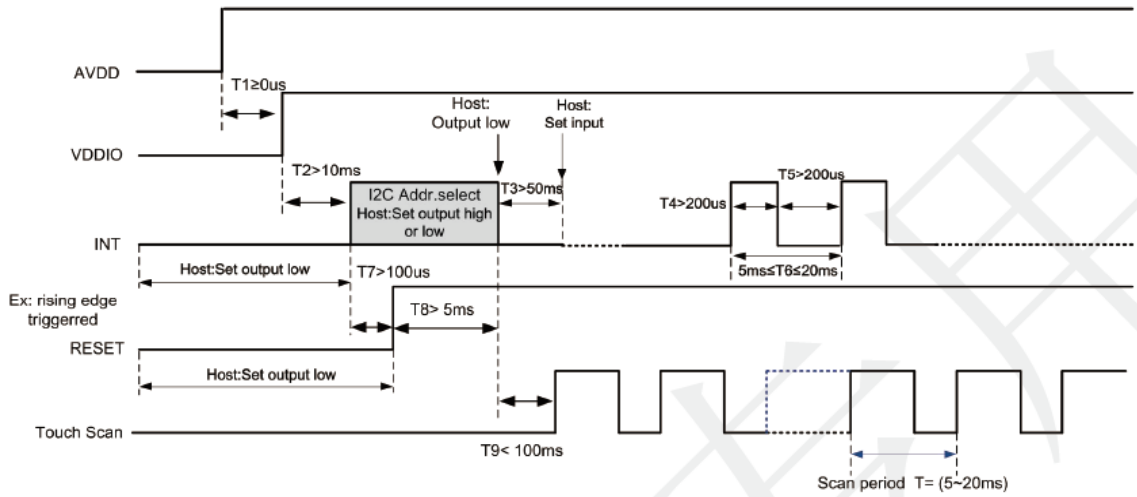
Parameter	Symbol	Min.	Max.	Unit
SCL low period	t_{lo}	1.3	-	us
SCL high period	t_{hi}	0.6	-	us
SCL setup time for Start condition	t_{st1}	0.6	-	us
SCL setup time for Stop condition	t_{st3}	0.6	-	us
SCL hold time for Start condition	t_{hd1}	0.6	-	us
SDA setup time	t_{st2}	0.1	-	us
SDA hold time	t_{hd2}	0	-	us

Test condition 2: 3.3V host interface voltage, 400Kbps transmission rate, 2K pull-up resistor

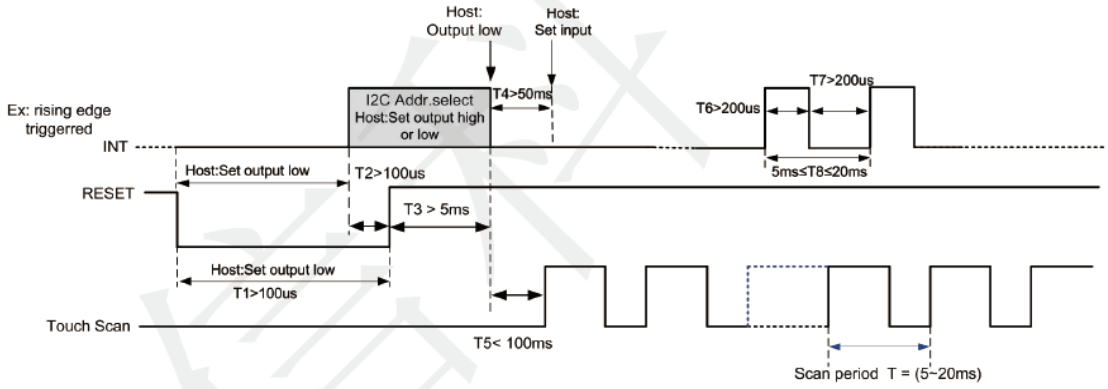
Parameter	Symbol	Min.	Max.	Unit
SCL low period	t_{lo}	1.3	-	us
SCL high period	t_{hi}	0.6	-	us
SCL setup time for Start condition	t_{st1}	0.6	-	us
SCL setup time for Stop condition	t_{st3}	0.6	-	us
SCL hold time for Start condition	t_{hd1}	0.6	-	us
SDA setup time	t_{st2}	0.1	-	us
SDA hold time	t_{hd2}	0	-	us

GT911 supports two I2C slave addresses: 0xBA/0xBB and 0x28/0x29. The host can select the address by changing the status of Reset and INT pins during the power-on initialization phase. See the diagram below for configuration methods and timings:

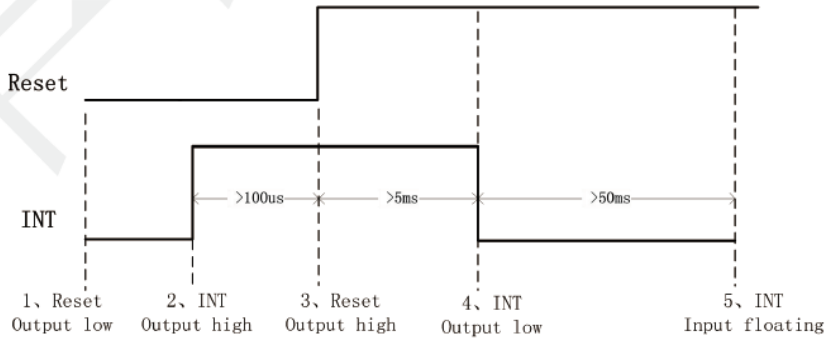
Power-on Timing:



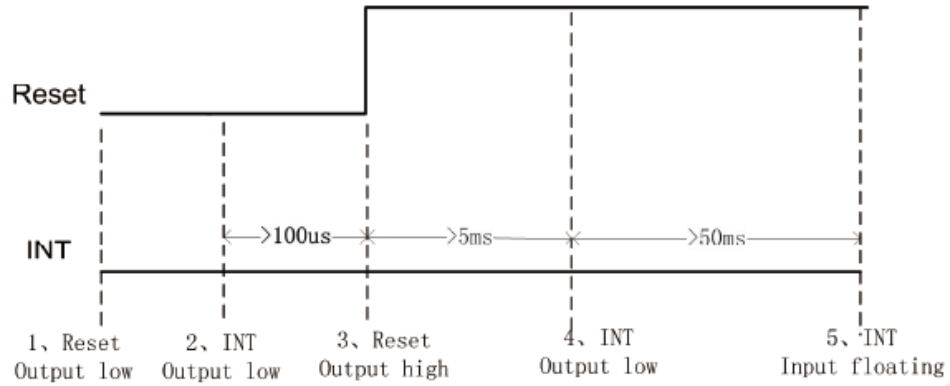
Timing for host resetting GT911:



Timing for setting slave address to 0x28/0x29:



Timing for setting slave address to 0xBA/0xBB:



a) Data Transmission

(For example：device address is 0xBA/0xBB)

Communication is always initiated by the host. Valid Start condition is signaled by pulling SDA line from “high” to “low” when SCL line is “high”. Data flow or address is transmitted after the Start condition.

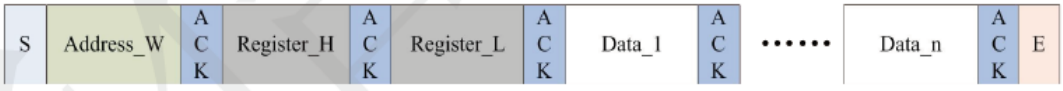
All slave devices connected to I^2C bus should detect the 8-bit address issued after Start condition and send the correct ACK. After receiving matching address, GT911 acknowledges by configuring SDA line as output port and pulling SDA line low during the ninth SCL cycle. When receiving unmatched address, namely, not 0XBA or 0XBB, GT911 will stay in an idle state.

For data bytes on SDA, each of 9 serial bits will be sent on nine SCL cycles. Each data byte consists of 8 valid data bits and one ACK or NACK bit sent by the recipient. The data transmission is valid when SCL line is “high”.

When communication is completed, the host will issue the STOP condition. Stop condition implies the transition of SDA line from “low” to “high” when SCL line is “high”.

b) Writing Data to GT911

(For example：device address is 0xBA/0xBB)



Timing for Write Operation

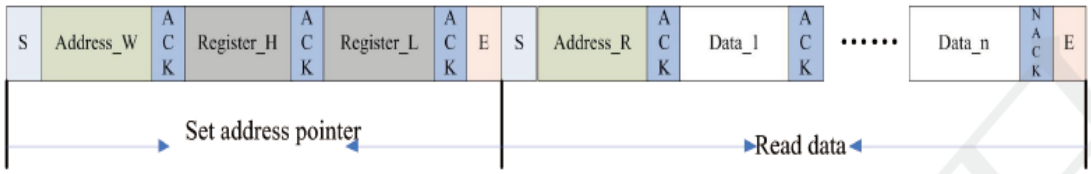
The diagram above displays the timing sequence of the host writing data onto GT911. First, the host issues a Start condition. Then, the host sends 0XBA (address bits and R/W bit; R/W bit as 0 indicates Write operation) to the slave device.

After receiving ACK, the host sends the 16-bit register address (where writing starts) and the 8-bit data bytes (to be written onto the register).

The location of the register address pointer will automatically add 1 after every Write Operation. Therefore, when the host needs to perform Write Operations on a group of registers of continuous addresses, it is able to write continuously. The Write Operation is terminated when the host issues the Stop condition.

c) Reading Data from GT911

(For example：device address is 0xBA/0xBB)



Timing for Read Operation

The diagram above is the timing sequence of the host reading data from GT911. First, the host issues a Start condition and sends 0XBA (address bits and R/W bit; R/W bit as 0 indicates Write operation) to the slave device.

After receiving ACK, the host sends the 16-bit register address (where reading starts) to the slave device. Then the host sets register addresses which need to be read.

Also after receiving ACK, the host issues the Start condition once again and sends 0XBB (Read Operation). After receiving ACK, the host starts to read data.

GT911 also supports continuous Read Operation and, by default, reads data continuously. Whenever receiving a byte of data, the host sends an ACK signal indicating successful reception. After receiving the last byte of data, the host sends a NACK signal followed by a STOP condition which terminates communication.

8 LCD Module Out-Going Quality Level

8.1 VISUAL & FUNCTION INSPECTION STANDARD

8.1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

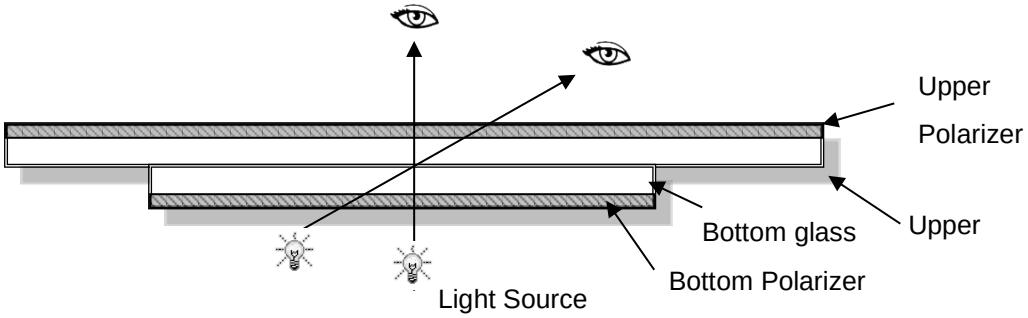
Temperature : 25±5℃

Humidity : 65%±10%RH

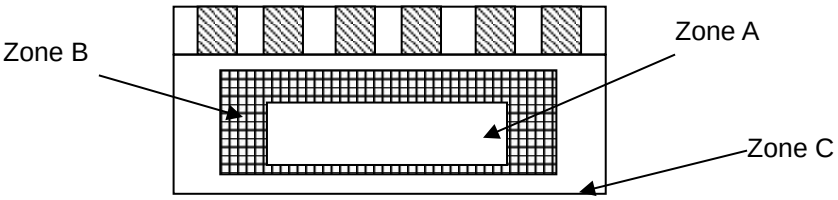
Viewing Angle : Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance:30-50cm



8.1.2 Definition



Zone A : Effective Viewing Area(Character or Digit can be seen)

Zone B : Viewing Area except Zone A

Zone C : Outside (Zone A+Zone B) which can not be seen after assembly by customer .)

Note:

As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer.

8.1.3 Sampling Plan

According to GB/T 2828-2003 ; , normal inspection, Class Ⅱ

AQL:

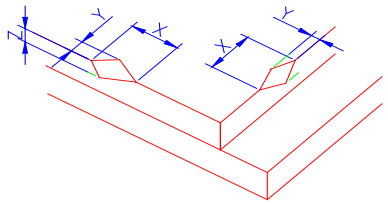
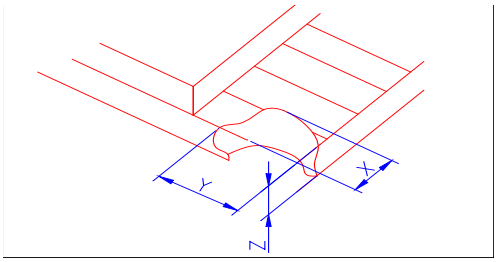
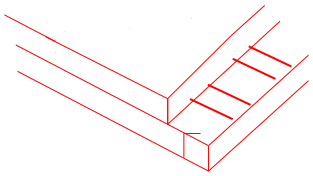
Major defect	Minor defect
0.65	1.5

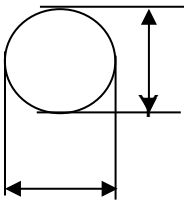
LCD: Liquid Crystal Display , TP: Touch Panel , LCM: Liquid Crystal Module

No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	1) No display, Open or miss line 2) Display abnormally, Short 3) Backlight no lighting, abnormal lighting. 4) TP no function	Major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	
4	Color tone	Color unevenness, refer to limited sample	Minor
5	Soldering appearance	Good soldering , Peeling off is not allowed.	
6	LCD/Polarizer/TP	Black/White spot/line, scratch, crack, etc.	

8.1.4 Criteria (Visual)

<table>
<tr><th>Number</th><th>Items</th><th>Criteria(mm)</th></tr>
<tr><td rowspan="3">1.0 LCD Crack/Broken

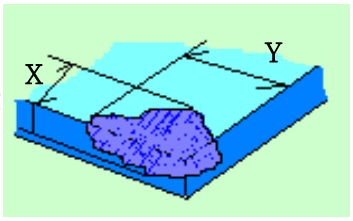
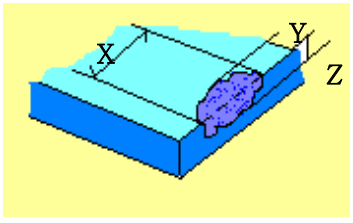
NOTE:
X: Length
Y: Width
Z: Height
L: Length of ITO,
T: Height of LCD</td><td>(1) The edge of LCD broken</td><td> 
<table><tr><th>X</th><th>Y</th><th>Z</th></tr><tr><td>≤3.0mm</td><td><Inner border line of the seal</td><td>≤T</td></tr></table></td></tr>
<tr><td>(2)LCD corner broken</td><td> 
<table><tr><th>X</th><th>Y</th><th>Z</th></tr><tr><td>≤3.0mm</td><td>≤L</td><td>≤T</td></tr></table></td></tr>
<tr><td>(3) LCD crack</td><td> 
Crack
Not allowed</td></tr>
</table>

<table>
<tr><th>Number</th><th>Items</th><th>Criteria (mm)</th></tr>
<tr><td>2.0</td><td>Spot defect
 
X
Φ=(X+Y)/2</td><td>① light dot（LCD/TP/Polarizer black/white spot , light dot, pinhole, dent, stain）
<table>
<tr><th rowspan="2">Zone
Size (mm)</th><th colspan="3">Accep□able Qty</th></tr>
<tr><th>A</th><th>B</th><th>C</th></tr>
<tr><td>Φ≤0.10</td><td colspan="2">Ignore</td><td rowspan="4">Ignor</td></tr>
<tr><td>0.10<Φ≤0.20</td><td colspan="2">3(distance≧10mm)</td></tr>
<tr><td>0.20<Φ≤0.25</td><td colspan="2">2</td></tr>
<tr><td>Φ＞0.25</td><td colspan="2">0</td></tr>
</table>
②Dim spot（LCD/TP/Polarizer dim dot, light leakage、dark spot）
<table>
<tr><th rowspan="2">Zone
Size (mm)</th><th colspan="3">Acceptable Qty</th></tr>
<tr><th>A</th><th>B</th><th>C</th></tr>
<tr><td>Φ≤0.1</td><td colspan="2">Ignore</td><td rowspan="4">Ignore</td></tr>
<tr><td>0.10<Φ≤0.20</td><td colspan="2">3(distance≧10mm)</td></tr>
<tr><td>0.20<Φ≤0.30</td><td colspan="2">2</td></tr>
<tr><td>Φ＞0.30</td><td colspan="2">0</td></tr>
</table>
③ Polarizer accidented spot
<table>
<tr><th rowspan="2">Zone
Size (mm)</th><th colspan="3">Acceptable Qty</th></tr>
<tr><th>A</th><th>B</th><th>C</th></tr>
<tr><td>Φ≤0.2</td><td colspan="2">Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.3<Φ≤0.5</td><td colspan="2">2(distance≧10mm)</td></tr>
<tr><td>Φ>0.5</td><td colspan="2">0</td></tr>
</table></td></tr>
<tr><td></td><td>Line defect (LCD/TP /Polarizer black/white line, scratch, stain)</td><td>
<table>
<tr><th rowspan="2">Width(mm)</th><th rowspan="2">Length(mm</th><th colspan="3">Acceptable Qty</th></tr>
<tr><th>A</th><th>B</th><th>C</th></tr>
<tr><td>Φ≤0.03</td><td>Igno□e</td><td colspan="2">Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.03<W≤0.05</td><td>L≤3.0</td><td colspan="2">N≤2</td></tr>
<tr><td>0.05<W≤0.08</td><td>L≤2.0</td><td colspan="2">N≤2</td></tr>
<tr><td>0.08<W</td><td colspan="4">Define as spot defect</td></tr>
</table></td></tr>
</table>

<table>
<tr><td>3.0</td><td>Polarizer Bubble</td><td>
<table>
<tr><td rowspan="2">Zone
Size (mm)</td><td colspan="3">Acceptable Qty</td></tr>
<tr><td>A</td><td>B</td><td>C</td></tr>
<tr><td>Φ≤0.2</td><td colspan="2">Ignore</td><td rowspan="4">Ignore</td></tr>
<tr><td>0.2<Φ≤0.4</td><td colspan="2">3(distance≧10□m)</td></tr>
<tr><td>0.4<Φ≤0.6</td><td colspan="2">2</td></tr>
<tr><td>0.6<Φ</td><td colspan="2">0</td></tr>
</table>
</td></tr>
<tr><td>4.0</td><td>SMT</td><td>According to IPC-A-610C class Ⅱ standard . Function defect and missing part are major defect ,the others are minor defect.</td></tr>
</table>

<table>
<tr><td rowspan="2"></td><td rowspan="2"></td><td>TP bubble/ accidented spot</td><td>
<table>
<tr><td rowspan="2">Size Φ(mm)</td><td colspan="3">Acceptable Qty</td></tr>
<tr><td>A</td><td>B</td><td>C</td></tr>
<tr><td>Φ≤0.1</td><td colspan="2">Ignore</td><td rowspan="4">Ignore</td></tr>
<tr><td>0.1<Φ≤0.25</td><td colspan="2">3（distance≧</td></tr>
<tr><td>0.25<Φ≤0.3</td><td colspan="2">2</td></tr>
<tr><td>0.3<Φ</td><td colspan="2">0</td></tr>
</table>
</td></tr>
<tr><td>Assembly deflection</td><td>beyond the edge of backlight ≤0.15mm</td></tr>
</table>

<table>
<tr>
<td rowspan="3">5.0</td>
<td rowspan="3">TP
Related</td>
<td>Newton
Ring</td>
<td>Newton Ring area>1/3 TP area NG

Newton Ring area≤1/3 TP area OK</td>
<td> 
</td>
</tr>
<tr>
<td>TP corner
broken
X：length
Y：width
Z：height</td>
<td>
<table>
<tr><th>X</th><th>Y</th><th>Z</th></tr>
<tr><td>X≤3.0mm</td><td>Y≤3.0mm</td><td>Z<LCD thicknes</td></tr>
</table>
*
Circuitry broken is not allowed.
</td>
<td> 
</td>
</tr>
<tr>
<td>TP edge
broken
X：length
Y：width
Z：height</td>
<td>
<table>
<tr><th>X</th><th>Y</th><th>Z</th></tr>
<tr><td>X≤6.0mm</td><td>Y≤2.0mm</td><td>Z<LCD thicknes</td></tr>
</table>
* Circuitry broken is not allowed.
</td>
<td> 
</td>
</tr>
</table>

Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed
5	TP no function	Not allowed

9. Reliability Test Result

9.1 Condition

Item	Condition	Sample Size	Test Result	Note
Low Temperature Operating Life test	-20℃, 96HR	3ea	pass	-
Thermal Humidity Operating Life test	70℃90%RH, 96HR	3ea	pass	-
Temperature Cycle ON/OFF test	-20℃ ↔ 70℃, ON/OFF, 20CYC	3ea	pass	(1)
High Temperature Storage test	80℃, 96HR	3ea	pass	-
Low Temperature Storage test	－30℃, 96HR	3ea	pass	-
ESD test	150pF, 330Ω , ±6KV(Contact)/± 8KV(Air), 5 points/panel, 10 times/point	3ea	pass	
Thermal Shock Resistance	The sample should be allowed to stand the following 5 cycles of operation: TSTL for 30 minutes -> normal temperature for 5 minutes -> TSTH for 30 minutes -> normal temperature for 5 minutes, as one cycle, then taking it out and drying it at normal temperature, and allowing it stand for 24 hours	3ea	pass	
Box Drop Test	1 Corner 3 Edges 6 faces, 66㎝(MEDIUM BOX)	1box	pass	-

Note (1) ON Time over 10 seconds, OFF Time under 10 seconds